

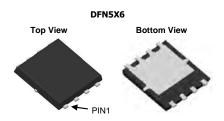
# STL85N6F3-VB Datasheet N-Channel 60 V (D-S) MOSFET

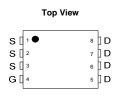
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS}(V)$ $R_{DS(on)}(\Omega)$			
60	0.006 at V <sub>GS</sub> = 10 V	80		
	0.007 at V <sub>GS</sub> = 4.5 V	65		

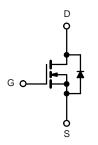
### **FEATURES**

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:









N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ( $T_C = 2$	25 °C, unless othe	rwise noted)		
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V <sub>GS</sub>	± 20	V
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 25 °C	I-	80	
	T <sub>C</sub> = 100 °C	l <sub>D</sub> –	65 <sup>a</sup>	
Pulsed Drain Current	I <sub>DM</sub>	100	А	
Continuous Source Current (Diode Conduction)	I <sub>S</sub>	70 <sup>a</sup>		
Avalanche Current		I <sub>AS</sub>	50	
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E <sub>AS</sub>	125	mJ
Maximum Dayar Dissinction	T <sub>C</sub> = 25 °C	ь	136	W
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub> –	3 <sup>b</sup> , 8.3 <sup>b, c</sup>	]
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Marrian un lunation to Ambienta	t ≤ 10 sec	- R <sub>thJA</sub>	15	18	°C/W	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		40	50		
Maximum Junction-to-Case		R <sub>thJC</sub>	0.85	1.1		

### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c.  $t \le 10 \text{ s}$ .



Daramatar	Cumbel	Toot Conditions	Min	<b>–</b> a	Max	l lm!4	
Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static	T	V 0.V I 050 A	T	T	1		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5		4		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			50		
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	60			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.006			
- 1 - 0 - 0 - 1 - 1 - h	D D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.010			
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 175 ^{\circ}\text{C}$		0.015		Ω	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A	0.007			1	
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S	
Dynamic			L				
Input Capacitance	C <sub>iss</sub>			2650			
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		470		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			225			
Total Gate Charge <sup>c</sup>	Qg			47	70		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		10		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, R_1 = 0.6 \Omega$		15	25	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		35	50		
Fall Time <sup>c</sup>	t <sub>f</sub>	, and the second		20	30		
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				60	Α	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		1	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/µs		45	100	ns	

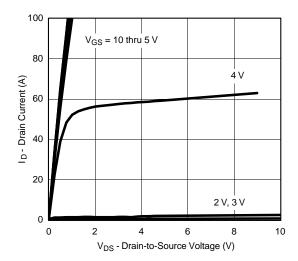
#### Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- c. Independent of operating temperature.

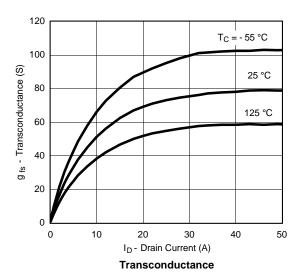
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



## TYPICAL CHARACTERISTICS (25 °C unless noted)



## **Output Characteristics**



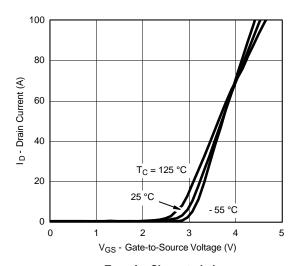
### 3500 3000 (Ld) 9 2500 2500 2500 0 1500 0 1500 0 1000 1000

 $V_{DS}$  - Drain-to-Source Voltage (V)  $\label{eq:capacitance}$ 

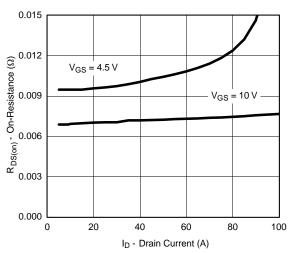
30

50

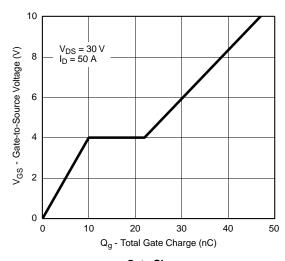
60



**Transfer Characteristics** 



On-Resistance vs. Drain Current



Gate Charge

服务热线:400-655-8788

0 C<sub>rss</sub>

10

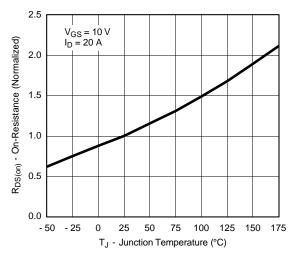
0

4000

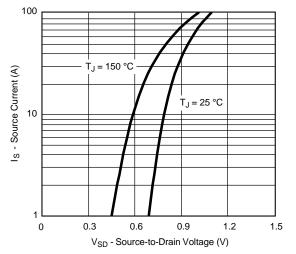
500



## TYPICAL CHARACTERISTICS (25 °C unless noted)



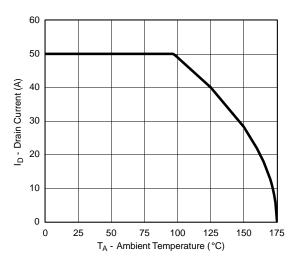
On-Resistance vs. Junction Temperature

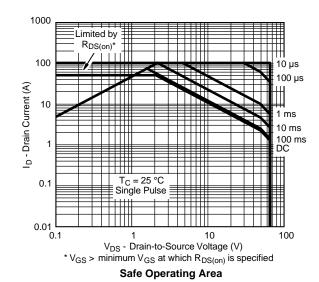


Source-Drain Diode Forward Voltage

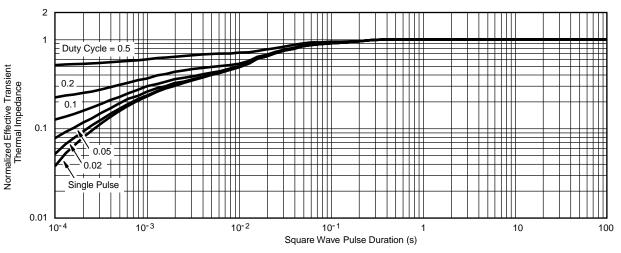


### THERMAL RATINGS





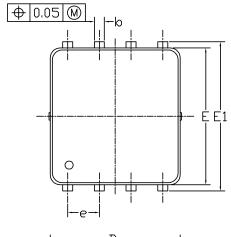
Maximum Drain Current vs. Ambient Temperature

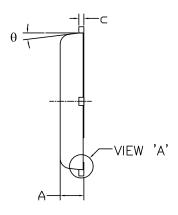


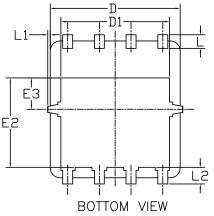
Normalized Thermal Transient Impedance, Junction-to-Case

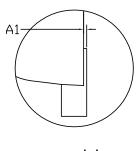


DFN5x6\_8L\_EP1\_P PACKAGE OUTLIN



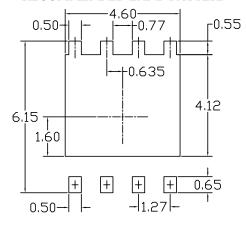






<u>VIEW 'A'</u> (SCALE 5:1)

### RECOMMENDED LAND PATTERN



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
A	0.85	0. 95	1.00	0.033	0.037	0.039
Al	0.00		0.05	0.000		0.002
b	0.30	0.40	0.50	0.012	0.016	0.020
С	0.15	0. 20	0. 25	0.006	0.008	0.010
D	5. 10	5. 20	5. 30	0. 201	0. 205	0. 209
D1	4. 25	4. 35	4. 45	0. 167	0. 171	0. 175
Е	5. 45	5. 55	5. 65	0.215	0.219	0. 222
E1	5. 95	6.05	6. 15	0. 234	0. 238	0. 242
E2	3. 525	3.625	3. 725	0.139	0.143	0. 147
E3	1. 175	1.275	1.375	0.046	0.050	0.054
e	1. 27 BSC			0.050 BSC		
L	0.45	0. 55	0.65	0.018	0.022	0.026
L1	0		0. 15	0		0.006
L2	0.68 REF			0.027 REF		
θ	0°		10°	0°		10°

### **NOTE**

- UNIT: mm
- 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
- 2. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.



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